

L Number	Hits	Search Text	DB	Time stamp
1	153	(438/\$.ccls. and cavity and via and (encapsula\$6 or underfill\$4) and @ad<=20020131) and (semiconductor adj packag\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/11 10:10
3	3	((("6507102") or ("6395578") or ("5596231")).PN.	USPAT	2003/07/11 10:45
-	315	438/106 and cavity and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/07 12:05
-	287	(438/106 and cavity and via) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:29
-	2203	438/106.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:28
-	191	438/106.ccls. and cavity and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:13
-	166	(438/106.ccls. and cavity and via) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:14
-	666	438/\$.ccls. and cavity and via and (encapsula\$6 or underfill\$4) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:30
-	1605	257/\$.ccls. and cavity and via and (encapsula\$6 or underfill\$4) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:31
-	415	(257/\$.ccls. and cavity and via and (encapsula\$6 or underfill\$4) and @ad<=20020131) and (semiconductor adj packag\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:32
-	537	(semiconductor adj packag\$6) and cavity and via and (encapsula\$6 or underfill\$4) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/07 12:07
-	1327	438/106.ccls. and (cavity or via or aperture or open\$4 or trenches or holes)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/07 12:07
-	537	(semiconductor adj packag\$6) and cavity and via and (encapsula\$6 or underfill\$4) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/07 12:08
-	427	(438/106.ccls. and (cavity or via or aperture or open\$4 or trenches or holes)) and (encapsula\$6 or underfill\$4) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/07 12:19